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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: MOECKLY ET AL. Examiner: UNKNOWN
Serial No.: 10/751,091 Group Art Unit: 1755
Filed: JANUARY 2, 2004 Docket: 10467.43USI2
Confirmation No.: 2150
Due Date: MAY 29, 2005 (30 DAY DATE)
Title: HIGH-TEMPERATURE SUPERCONDUCTOR DEVICES AND METHODS OF FORMING THE SAME

CERTIFICATE UNDER 37 CFR 1.8:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 on May 20, 2005.

By: 

Name: Kristine A. Wacek

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

23552

PATENT TRADEMARK OFFICE

Sir:

We are transmitting herewith the attached:

- ☒ Transmittal Sheet in duplicate containing Certificate of Mailing
- ☒ Information Disclosure Statement, Form 1449, 6 Reference(s), Copy of International Search Report
- ☒ Return postcard

Please consider this a PETITION FOR EXTENSION OF TIME for a sufficient number of months to enter these papers or any future reply, if appropriate. Please charge any additional fees or credit overpayment to Deposit Account No. 13-2725. A duplicate of this sheet is enclosed.

Merchant & Gould P.C.
P.O. Box 2903
Minneapolis, MN 55402-0903
612.332.5300

By: 

Name: Brian H. Batzli

Reg. No.: 32,960

BBatzli:PLSkaw



S/N 10/751,091

PATENT

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By:

Kristine A. Wacek

Name: Kristine A. Wacek

INFORMATION DISCLOSURE STATEMENT (37 C.F.R. § 1.97(b))

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

23552

PATENT TRADEMARK OFFICE

Dear Sir:

With regard to the above-identified application, the items of information listed on the enclosed Form 1449 are brought to the attention of the Examiner. Enclosed for the Examiner's information is a copy of the International Search Report. At least some of the references were recently cited in an International Search Report mailed April 29, 2005.

This statement should be considered because it is submitted before the mailing date of a first Office Action on-the-merits. Accordingly, no fee is due for consideration of the items listed on the enclosed Form 1449.

Certification Under 37 C.F.R. § 1.704(d)

In accordance with 37 C.F.R. § 1.704(d), the undersigned hereby certifies that each item listed on the enclosed Form 1449 was cited in a communication from a foreign patent office in a counterpart application, and that this communication was not received by any individual designated in 37 C.F.R. § 1.56(c) more than thirty (30) days prior to the filing of this Information

Disclosure Statement. Accordingly, no patent term adjustment is due for the filing of this Information Disclosure Statement.

A copy of any foreign patent document or "Other Document" listed on the Form 1449 is enclosed, in accordance with 37 C.F.R. §1.98(a)(2). Because this application was filed after June 30, 2003, copies of the U.S. Patents and U.S. patent publications listed on the enclosed Form 1449 are not provided.

No representation is made that a reference is "prior art" within the meaning of 35 U.S.C. §§ 102 and 103 and Applicants reserve the right, pursuant to 37 C.F.R. § 1.131 or otherwise, to establish that the reference(s) are not "prior art." Moreover, Applicants do not represent that a reference has been thoroughly reviewed or that any relevance of any portion of a reference is intended.

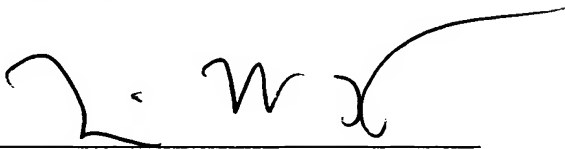
Consideration of the items listed is respectfully requested. Pursuant to the provisions of M.P.E.P. 609, it is requested that the Examiner return a copy of the attached Form 1449, marked as being considered and initialed by the Examiner, to the undersigned with the next official communication.

Please charge any additional fees or credit any overpayment to Deposit Account No. 13-2725.

Respectfully submitted,

MERCHANT & GOULD P.C.
P.O. Box 2903
Minneapolis, Minnesota 55402-0903
(612) 332-5300

Date: 19 May 2005



Brian H. Batzli
Reg. No. 32,960
BHB:PLSkaw

FORM 1449 INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)	Docket Number: 10467.43US12	Application Number: 10/751,091
	Applicant: MOECKLY ET AL.	
	Filing Date: 01/02/2004	Group Art Unit: 1755

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	2004/0134967 A1	07/15/2004	Moeckly et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		Char, K. et al., "High T_c superconductor-normal-superconductor Josephson junctions using CaRuO_3 as the metallic barrier," <i>Applied Physics Letters</i> , Vol. 62, No. 2, pp. 196-198 (January 11, 1993)
		Harada, K. et al., "Fabrication of All-High- T_c Josephson Junction Using As-Grown $\text{YBa}_2\text{Cu}_3\text{O}_x$ Thin Films," <i>Japanese Journal of Applied Physics</i> , Vol. 30, No. 8A, Part 2, pp. L1387-1389 (August 1, 1991)
		Huang, Y. et al., "The effect of microstructure on the electrical properties of YBCO interface-engineered Josephson junctions," <i>Physica C</i> , Vol. 314, pp. 36-42 (1999)
		Makita, T. et al., "Fabrication of Ramp-Edge Junction with $\text{NdBa}_2\text{Cu}_3\text{O}_y$ -Based Interface-Modified Barrier," <i>Jpn. J. Appl. Phys.</i> , Vol. 39, Part 2, No. 7B, pp. L730-L732 (July 15, 2000)
		Makita, T. et al., "Fabrication and Characterization of Y-Ba-Cu-O and Nd-Ba-Cu-O Ramp-Edge Junctions with an Interface-Modified Barrier," <i>IEEE Transactions on Applied Superconductivity</i> , Vol. 11, No. 1, pp. 155-158 (March 2001)
		Moeckly, B. et al., "Interface-Engineered High- T_c Josephson Junctions," <i>Applied Superconductors</i> , Vol. 6, Nos. 7-9, pp. 317-323 (1998)

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PATENT TRADEMARK OFFICE

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form for next communication to the Applicant.	